Special Issue

Wafer Level Packaging of MEMS

Message from the Guest Editor

Packaging is essential for the practical use of MEMS, in terms of performance and reliability. The electronics market has been continuously requiring the downsizing and cost reduction of MEMS, and, thus, wafer-level packaging is becoming more important and replacing conventional die-level packaging. One of important features of the wafer-level packaging of MEMS is that it often needs the device cavity, which is hermetically sealed. Therefore, hermetic/vacuum sealing and electrical feedthrough from the sealed cavity are key technologies. On the other hand, emerging devices need new types of packaging, for example, biocompatible and flexible packaging, which are also attracting a great deal of attention. Test, reliability control, wiring, dicing, chip-level integration and material development related to the wafer-level packaging of MEMS are also included in the scope of this Special Issue. Wafer-level packaging is strongly connected to the integration of multiple components, and, thus, papers about wafer-level integration are also welcome.

Guest Editor

Prof. Dr. Shuji Tanaka

Department of Robotics, Graduate School of Engineering, Tohoku University 6-6-01 Aramaki Aza Aoba, Aoba-ku, Sendai, Miyagi 980-8579, Japan

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Micromachines
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
micromachines@mdpi.com

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Editor-in-Chief

Prof. Dr. Ai-Qun Liu
1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

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